

ABSTRACT OF THE DISCLOSURE

Disclosed is a semiconductor package capable of realizing a small and compact size and improving the reliability and the fabrication method of the same. The disclosed comprises: a main semiconductor chip having a plurality of main chip pads and operating as a lead frame or a substrate; a plurality of metal patterns electrically connected to each corresponding main chip pad and having electrodes formed on both ends; one or more sub semiconductor chip adhered to the main semiconductor chip by adhering bumps formed on a plurality of sub chip pads to each corresponding electrode; a dam formed on the main semiconductor chip in a shape surrounding the inner electrodes except for the outer electrodes on the outmost region of the main semiconductor chip; filling materials filled up in the dam; and a plurality of solder balls adhered on the outmost electrodes.